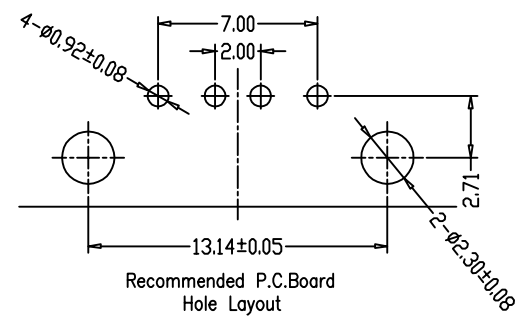
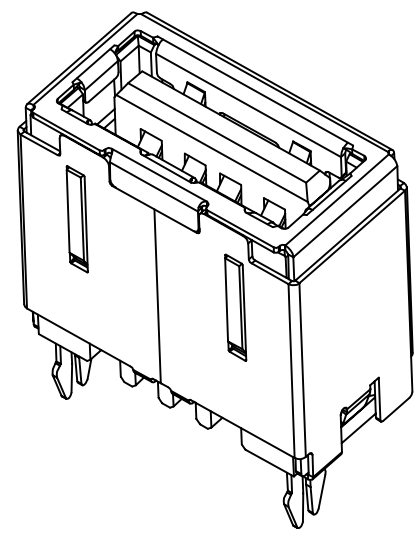
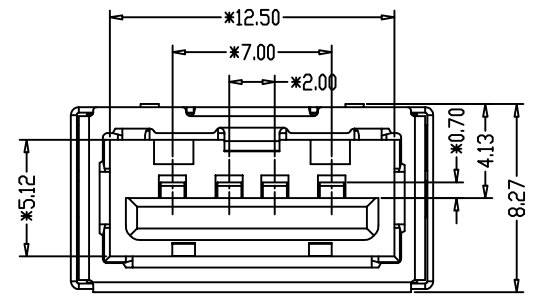


1 2 3 4 5 6 7

A
B
C
D
E

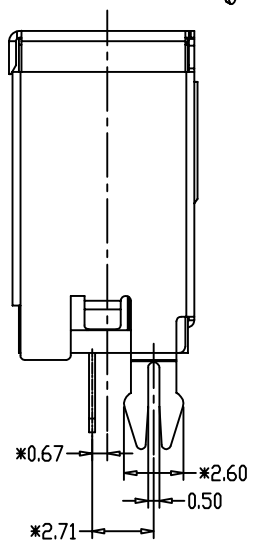
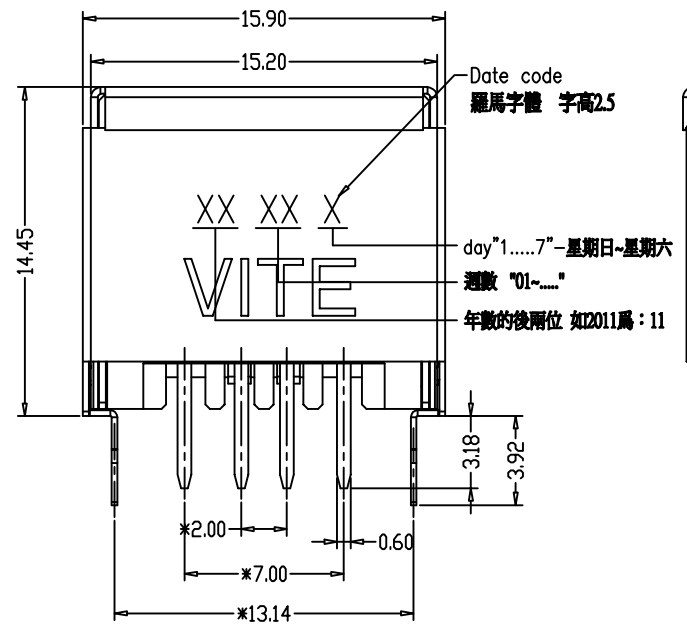
A
B
C
D
E



Plat No.	CONTACT PLATING	MATERIAL
20032-T1	GOLD/TIN PLATED (接觸區先鍍純鎳30μ)	LCP
20032-T2	GOLD(30μ)/TIN PLATED	LCP

- NOTES:
 MATERIAL:
 1.INSULATOR: LCP 94 UL-V0 Color: Black
 2.CONTACT: BRASS C2680 T=0.25mm
 3.CONTACT PLATED: GOLD PLATED OVER NICKEL ON CONTACT AREA
 TIN PLATED OVER NICKEL ON SOLDER TAIL.
 4.SHELL: C2680 T=0.30mm
 5.SHELL PLATED: NICKEL OVER COPPER

- SPECIFICATION:
 1.CONTACT CURRENT RATING: 1AMP. 30V AC
 2.INSULATION RESISTANCE:1000M ohm MIN. AT 250V DC
 3.DIELECTRIC WITHSTANDING VOLTAGE: AC 500V(R.M.S)/1 MINUTE
 4.CONTACT RESISTANCE: 30 Mini OHM Max(intial)
 RoHS compliant
 **標示是重點管控尺寸



尚益科技有限公司
 JMSSCONN TECHNOLOGY CO., LTD.

PROJ	SCALE : F DO NOT SCALE DWG	MOLD NO 20032-T2	REV. X1
APP		MODEL	FILE NO
CHK		UNIT	SIZE
DGN		MM	A4
DRW	HSIEH 2016.11.16	SHT 1 OF 1	

1 2 3 4 5 6 7